TXGA

1. Scope

This specification covers the micro USB Female SMT type connector series.

2. Applicable documents

The following documents form a part of this specification to the extent specified herewith. In the event of conflict between the requirements of the specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of the specification and the referenced documents, this speci- fication shall take precedence.

3. Ordering information

Refer to the drawing.

4. Connector dimensions

Refer to the drawing.

5. Material

Housing: LCP (UL 94V-0) Color: Refer to the drawing. Terminal: Copper alloy Plating: Gold plated Shell: SUS 304 Plating: Tin plated

6. Accommodated P.C.B layout

Refer to the drawing.

7. Rating

Operating voltage(Max.)	30V DC/AC
Current rating(Max.)	1.0A
Temperature range-operating	-25°C +85°C

8. Performance

Test item	Standards	Requirement		
Electrical Performance				
Contact Resistance	30 mΩ Max.	Mate applicable micro USB plug, measure by dry circuit, 20mV Max., 100mA. (EIA-364-23)		
Insulation Resistance	100 MΩ Min.	Mate applicable micro USB plug, apply 100V DC for 1 minute between adjacent terminal or ground. (EIA-364-21)		
Dielectric Strength	No breakdown	Mate applicable micro USB plug; apply 100V AC for 1 minute between adjacent terminal or ground. (EIA 364-20)		



TXGA Industrial Electronics (S.Z.) Co., Ltd Micro USB 5Circuits FUS428 series

Test item	Standa	irds	Requirement		
		Mechanical Pe	erformance		
Insertion Force	3.57kgf Max.		Insert the standard gauge at the speed rate of 12.5mm per minute, Mate applicable micro USB plug. (EIA-364-13)		
Withdrawal Force	0.82kgf Min.		ndrawal Force 0.82kgf Min.		Withdraw the standard gauge at the speed rate of 12.5mm per minute, Mate applicable micro USB plug. (EIA-364-13)
Durability	Contact Resistance 50 mΩ Max.		MICRO USB Receptacle Mate applicable micro USB plug up to 5000 cycles repeatedly. (EIA-364-09)		
	Env	ironmental Perfor	mance and others		
Heat Resistance	Appearance	No damage	85+5° 06 hours		
	Contact Resistance	50 mΩ Max.			
Cold Posictanco	Appearance	No damage	-25+5℃ 96 hours		
	Contact Resistance	50 mΩ Max.	-2010 0, 00 mours.		
	Appearance	No damage			
Humidity	Contact Resistance	50 mΩ Max.	Temperature : 40±2℃. Relative Humidity : 90~95%.		
Turnary	Dielectric strength	No Breakdown at 100V AC /minute	Duration : 96 hours. (EIA 364-31)		
	Insulation Resistance	1000 MΩ			
	Appearance	No Damage	Mated connector shall be set to temperature cycling for 5 cycles of which 1 cycle consists of: 1>.+25°C ~ 3 minutes		
	Contact Resistance	50mΩ Max.	2>25°C ~ 30 minutes 3>.+25°C ~ 3 minutes 4>.+85°C ~ 30 minutes		
	Appearance	No damage	48±2hours exposure to a salt spray from the 5±1%, solution		
Salt Spray	Contact Resistance	50 mΩ Max.	recondition the room temperature for 1 hour. (EIA 364-26)		



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Test item	Standards	Requirement		
Solderability	The surface of the portion to be soldered shall at least 95% covered with new solder coating.	Solder Temperature: 245±3℃, Duration: 5±0.5 seconds. (EIA 364-52)		
Resistance To Solder Heat	No mechanical defect on housing or other parts.	Temperature: 250℃ Max., 10±0.5 seconds. (Lead-Free)		



Reference infrared reflow condition (Lead-Free)

9. Test sequences identification

		Test Group					
No.	Test or Examination	А	В	С	D	E	F
		Test Sequence					
1	Examination of Product	1,4	1,8	1,7	1,6	1,3	1,3
2	Dielectric Strength	3		6			
3	Contact Resistance		2,5,7	4	3,5		
4	Insulation Resistance	2		5			
5	Insertion Force	5					
6	Withdrawal Force		3				
7	Contact Retention Force	6					
8	Durability		4				
9	Heat Resistance			2			
10	Cold Resistance		6				
11	Humidity			3			
12	Temperature cycling				2		
13	Solder ability					2	
14	Resistance to Soldering Heat						2
15	Salt Spray				4		